



Sep. 4, 2008

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/821,546 Mar. 30, 2001

JIN-YUAN LEE ET AL.

“A STRUCTURE AND MANUFACTURING
METHOD OF CHIP SCALE PACKAGE”

Grp. Art Unit: 2811

VU, HUNG K.

Please Enter.

AMENDMENT AFTER NOTICE OF ALLOWANCE

Thank you.

/HV/ Dear Sir:

Please enter the following amendment to the above-identified patent application and
consider the remarks as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal
Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box
1450, Alexandria, VA 22313-1450, on Sept. 12, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date Sept. 12, 2008

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 34 of this paper.